

Statement of product compliance with the RoHS 3 directive; Directive 2011/65/EU of the European Parliament with amendment by Commission Delegated Directive (EU) 2015/863. <https://eur-lex.europa.eu/legal-content/EN/TXT/?uri=CELEX%3A02011L0065-20211101&qid=1649076521945>

PCB's produced at PRI-DANA comply with the RoHS 3 directive as stated in the table below.

Material/process	Compliance	Note
Base materials		
Laminates	YES	PBDE- and PBB free
Prepreg	YES	PBDE- and PBB free
Cu foil	YES	Chromium free
Through hole plating		
Electroless Cu	YES	Pure Cu deposit
Galvanic plating		
Galvanic Cu	YES	Pure Cu deposit (>99,50 %)
Galvanic Au	YES	Hard Au (contains Ni) and Soft Au (>99,99 % Au)
Galvanic Ni	YES	Pure Ni deposit
Surface finish		
Solder mask	YES	PBDE- and PBB free
Serigraphic print	YES	PBDE- and PBB free
Solder finishing		
Electroless Ni, immersion Au	YES	Ni-P and pure Au deposits
Immersion Sn	YES	Sn deposit (contains Ag)
Immersion Ag	YES	Ag deposit
Lead free Hot Air Levelling	YES	SN 100 C (Nihon Superior)
Traditional Hot Air Levelling	NO	37% Pb in alloy
Fused Sn/Pb	NO	37% Pb in alloy

The above information has been retrieved from all PRI-DANA's suppliers of raw materials and process chemistry. The following maximum limits have been used in the assessment of compliance:

Cadmium (Cd):	100 ppm
Lead (Pb):	1000 ppm
Mercury (Hg):	1000 ppm
Hexavalent chromium (Cr ⁶⁺):	1000 ppm
PBB:	1000 ppm
PBDE:	1000 ppm
DEHP:	1000 ppm
BBP:	1000 ppm
DBP:	1000 ppm
DIBP:	1000 ppm

Change log:

Date:	Replaces:	Change description:
2019-10-08	None	New document
2020-05-04	Rev. 01, 2019-10-08	Updated link to newest version of the legal text
2020-11-11	Rev. 02, 2020-05-04	Updated link to newest version of the legal text
2022-04-04	Rev. 03, 2020-11-11	Updated link to newest version of the legal text
2022-09-02	Rev. 04, 2022-04-04	Updated, editorial modifications

Link to document on website.